

MODULE CIRCUIT BOARD FOR SEMICONDUCTOR DEVICE HAVING BARRIERS TO ISOLATE I/O TERMINALS FROM SOLDER

CROSS-REFERENCE TO RELATED APPLICATION

5 This application claims the priority benefit of Japanese Patent Application No. 10-354757, filed December 14, 1998, the entire subject matter of which is incorporated herein of reference.

BACKGROUND OF THE INVENTION

10 1. Field of the invention

 The invention relates to a module circuit board including a plurality of I/O terminals disposed at an edge of the board, a plurality of soldering pads on its surface for mounting parts such as semiconductor devices, and a barrier formed on its surface to isolate the I/O terminals from solder.

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2. Description of the related art

 A module circuit board for mounting flat type package ICs using a Surface-Mounted Device includes a plurality of I/O terminals plated of gold or flash gold which is formed on its one edge, a plurality of soldering pads on its surface on which the ICs
20 are mounted using a solder reflow process, and a solder resist film formed on the circuit board. In the solder reflow process, some problems occur. That is, during the performance of the solder reflow process, solder balls are formed from melted

solder. The solder ball is moved on the resist film, which is disposed between the pads and the terminals. If the solder ball reached the terminal is adhered to the terminal, the circuit board will be defective. To avoid this problem, the following countermeasure has been taken.

- 5 (1) To avoid the formation of the solder ball, some conditions of the reflow process, including the temperature, are changed.
- (2) To prevent the solder ball from reaching the terminal, the terminal is sealed with a tape before the reflow process.

In the measure (1), the frequency that the solder ball is formed can be
10 decreased. However, it is difficult to eliminate the formation of the solder ball completely. In the measure (2), the cost performance is not effective because of sealing and removing the tape. Further, if the tape adhesive remains on the terminal, it becomes a problem when the board is connected to the other parts.

15 SUMMARY OF THE INVENTION

An objective of the invention to provide a module circuit board for a semiconductor device having barriers to isolate I/O terminals from solder.

To achieve this objective, a module circuit board for a semiconductor device includes a plurality of pads, on which the semiconductor device is mounted, formed
20 on of the board, a plurality of terminals formed on a side edge of the board, a resist film covering an area between the pads and the terminal on the board and a barrier formed between the pads and the terminals.

BRIEF DESCRIPTION OF THE DRAWINGS

The invention will be more particularly described with reference to the accompanying drawings in which:

5 Fig. 1(a) is a plan view of a module circuit board of the first embodiment of the invention,

 Fig. 1(b) is an enlarged sectional view taken along line A-A' shown in Fig. 1(a),

 Fig. 2(a) is a plan view of a module circuit board of the second embodiment of the invention,

10 Fig. 2(b) is an enlarged sectional view taken along line B-B' shown in Fig. 2(a),

 Fig. 3(a) is a plan view of a module circuit board of the third embodiment of the invention,

 Fig. 3(b) is an enlarged sectional view taken along line C-C' shown in Fig. 3(a),

 Fig. 4(a) is a plan view of a module circuit board of the fourth embodiment of the invention,

 Fig. 4(b) is an enlarged sectional view taken along line D-D' shown in Fig. 4(a),

 Fig. 5(a) is a plan view of a module circuit board of the fifth embodiment of the invention,

 Fig. 5(b) is an enlarged sectional view taken along line E-E' shown in Fig. 5(a),

20 Fig. 6(a) is a plan view of a module circuit board of the sixth embodiment of the invention, and

 Fig. 6(b) is an enlarged sectional view taken along line F-F' shown in Fig. 6(a).

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

Referring to Figs. 1(a) and 1(b), a module circuit board 1 for mounting a Surface-Mounted Device includes a plurality of I/O terminals 2 plated of gold or flash gold which is formed on its one edge and a plurality of soldering pads 3 on its surface on which some semiconductor devices are mounted using a solder reflow process. As the other area of the board 1 is covered by a solder resist film 4 having a thickness of 20 μ m, the solder layer can not be formed on the other area of the board 1 which is covered by the film 4. A wall 5 is formed on the resist film 4 between the terminals 2 and pads 3, along the terminals 2. Preferably, the wall 5 is disposed in the middle between the terminals 2 and pads 3, and preferably a little closer to the terminals 2. The wall 5 has a length of about 10mm, so as to extend past the group of the terminals 2, and has a width of about 0.5 mm. The wall 5 acts as a barrier to isolate the terminals 2 from solder. The wall 5 is formed using a screen print method, with resin having high viscosity, such as epoxy. The height h of the wall is not less than 0.1mm which is larger than a diameter of a solder ball which is formed during a solder reflow process.

According to this first embodiment, if the solder ball is formed when the ICs are mounted on the board 1 during the solder reflow process, the solder ball can not get to the terminals 2 because the wall 5 acts as the barrier. Therefore, as it is not necessary to seal the terminals 2 with tape, process time can be reduced, and the tape adhesive does not remain on the terminals 2. As a result, the number of

defective boards is dramatically decreased, and the uniform quality of the board can be achieved.

Referring to Figs. 2(a) and 2(b), two walls 15a, 15b are formed on the resist film 4 between the terminals 2 and pads 3, along the terminals 2. The first wall 15a
5 is disposed parallel to the second wall 15b. Each wall has a length of about 10mm, so as to extend past the group of the terminals 2, and has a width of about 0.5 mm. The walls 15a, 15b act as barriers to isolate the terminals 2 from solder. The walls 15a, 15b are formed by the same method described in the first embodiment. The height h of each wall is not less than 0.1mm, which is larger than a diameter of a
10 solder ball which is formed during a solder reflow process.

According to the second embodiment of the invention, if the solder ball is formed when the ICs are mounted on the board 1 using the solder reflow process, the solder ball can not get to the terminals 2 because the first wall 15a and the second wall 15b act together as the barrier. Further, if the solder ball runs over the
15 first wall 15a, the solder ball will be stacked between the first wall 15a and the second wall 15b because of a surface tension effect of the solder ball. Therefore, the barrier effect of the second embodiment is more than twice as high as the first embodiment.

Referring to Figs. 3(a) and 3(b), an elongated trench 25 is formed on the resist
20 film 4 between the terminals 2 and pads 3, along the terminals 2. The surface of the board 1 is exposed at the bottom of the trench 25. The trench 25 acts as a barrier to isolate the terminals 2 from solder. The trench 25 has a width of about 0.5mm, and

is formed with the resist film 4. The length of the trench is a little longer than the width of a terminal group, i.e., it extends past the terminal group.

According to this third embodiment of the invention, if the solder ball is formed when the ICs are mounted on the board 1 using the solder reflow process, the solder
5 ball can not get to the terminals 2 because the solder ball will be stacked in the trench 25 which acts as the barrier. Further, since the trench is formed together with the resist film 4, no additional process to fabricate the board is necessary, as compared to the first and second embodiments. Furthermore, as the circuit patterns formed on the board 1 are plated electrolessly with flash Au, the reflowed solder does not
10 have any influence on the circuit patterns even if the solder runs into the trench 25.

Referring to Figs. 4(a) and 4(b), two elongated trenches 35a, 35b are formed on the resist film 4 between the terminals 2 and pads 3, along the terminals 2. The surface of the board 1 is exposed at the bottom of the trenches 35a, 35b. The first trench 35a is disposed and spaced parallel to the second trench 35b. The distance
15 between the trenches 35a, 35b is about 1mm. The trenches 35a, 35b act as barriers to isolate the terminals 2 from solder. Each trench 35a, 35b has a width of about 1mm, and is formed with the resist film 4. The length of each trench is a little longer than the width of a terminal group, i.e., it extends past the terminal group.

According to this fourth embodiment of the invention, if the solder ball is
20 formed when the ICs are mounted on the board 1 using the solder reflow process, the solder ball can not get to the terminals 2 because the solder ball will be stacked in the first trench 35a. If the solder ball runs over the first trench 35a, the solder ball

will be stacked in the second trench 35b. Even if the distance between the trenches 35a, 35b is smaller than the diameter of the solder ball, the solder ball will be stacked in the both trenches 35a, 35b because of a surface tension effect of the solder ball. Therefore, the barrier effect of the fourth embodiment is more than twice as high as the third embodiment. Furthermore, similar to the third embodiment, no additional processes to fabricate the board are necessary, as compared to the first and second embodiments because the trench is formed together with the resist film 4.

Referring to Figs. 5(a) and 5(b), an elongated trench 45 is formed on the resist film 4 between the terminals 2 and pads 3, along the terminals 2. A metal pattern 46 made of Cu is formed on the board 1 in the trench 45. The thickness of the metal pattern 46 is about 30 μ m. The metal pattern 46 has a width of about 0.1mm, and is formed with the other circuit patterns formed on the board. The metal pattern 46 can be connected to a power supply line 47 formed on the board. However, the metal pattern 46 is not connected to some signal lines 48 and some ground lines 49. The metal pattern 46 acts as a barrier to isolate the terminals 2 from solder.

According to the fifth embodiment of the invention, if the solder ball is formed when the ICs are mounted on the board 1 by the solder reflow process, the solder ball can not get to the terminals 2 because the solder ball will adhere to the metal pattern 46, which acts as the barrier. Further, as the metal pattern 46 is formed together with the other circuit pattern such as the power supply line 47, no additional processes to fabricate the board are necessary.

Referring to Figs. 6(a) and 6(b), an elongated trench 55 is formed on the resist

film 4 between the terminals 2 and pads 3, along the terminals 2. Furthermore, a wall 56, which is formed using the same method described in the first and second embodiments is formed on the resist film 4. The wall 56 is disposed between the trench 55 and terminals 2. The height h of the wall is not less than 0.1mm, which is larger than a diameter of a solder ball which is formed during the solder reflow process. The surface of the board 1 is exposed at the bottom of the trench 55. The trench 55 acts as a first barrier to isolate the terminals 2 from solder. The wall 56 acts as a second barrier to further isolate the terminals 2 from solder. Each length of the trench 55 and the wall 56 is a little longer than the width of a terminal group, i.e., they extend past the terminal group.

According to the sixth embodiment of the invention, if the solder ball is formed when the ICs are mounted on the board 1 using the solder reflow process, the solder ball can not get to the terminals 2 because the solder ball will be stacked in the trench 55. If the solder ball runs over the trench 55, the wall 56 as the second barrier dams the solder ball. If the distance between the trench 55 and the wall 56 is smaller than the diameter of the solder ball, the solder ball will be stacked between the trench 55 and the wall 56 strongly because of a surface tension effect of the solder ball.

While the present invention has been described with reference to illustrative embodiments, this description is not intended to be construed in a limiting sense. Various modifications of the illustrated embodiments, as well as other embodiments of the invention, will be apparent to those skilled in the art on reference to this description. For example, although the walls 5, 15a, 15b, 56 are formed of

resin in the first, second and sixth embodiment, these walls 5, 15a, 15b, 56 can be formed of metal, such as gold to which the solder can be adhered easily. If the wall is formed of gold, the solder ball is not only dammed by the wall but also will be adhered onto the wall. Such a gold wall may be pasted on the resist film. Further, 5 although two walls are formed in the second embodiment, it is possible to further increase the number of walls. Furthermore, although two trenches are formed in the fourth embodiment, it is possible to further increase the number of trenches. Therefore, the appended claims are intended cover any such modifications or embodiments as falls within the true scope of the invention.